

Prateek Pradhan

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Summary

Results-driven product and technology leader with 6+ years of experience building scalable wireless solutions. Strong track record of driving product growth through Gen-AI automation, agile practices, global B2B alignment, and cross-functional collaboration.

Professional Experience

Software Development Engineer , Firmware ICT3 | Apple | Bengaluru

Aug-2022 – Apr-2025

- Pioneered Apple's most energy-efficient modem, achieving 25% lower power consumption as a founding software team member, enabling thinner iPhone designs with improved thermal and network management.
- Pioneered agentic AI automation for global product triage and debugging, achieving 95%+ accuracy and significantly reducing operational man-hours across worldwide teams.
- Developed an LLM-based code-review agent for software check-ins, cutting review turnaround and improving pre-merge defect detection.
- Led chip bring-up across 7+ functional areas for multiple cellular programs, owning end-to-end execution, architecture design, software development, and triage of 100+ issues/week to keep launches on schedule.
- Spearheaded an RF resource-sharing architecture, cutting power consumption by 27% and chip area/cost, enabling new band combinations that improved global reception and customer experience.
- Contributed to Emergency SOS via Satellite, enabling direct connectivity to emergency responders in areas without cellular coverage credited with documented life-saving rescues.
- Engineered a Multi-SIM feature, improving download speeds by 11% and call-drop performance, strengthening Apple's competitive edge in key dual-SIM markets.

Software Development Engineer| Qualcomm| Hyderabad

Nov 2019 – Aug 2022

- Led the RF design and support for LTE and V2X technology in the Snapdragon Auto5G/820 for vehicular-cloud (V2X) and autonomous car applications, contributing to \$1 billion in sales in 2021.
- Managed a 3-member team for a software subcomponent of the Qualcomm X70 5G chipset, designing pioneering 5G DSDA features for premium-tier phones and enhancing the customer experience.
- Ideated and implemented an R&D feature for thermal mitigation, preventing hardware component damage and failure due to excess heat.
- Collaborated with major OEMs (Apple, Samsung, Mercedes) to address customer-specific requirements using Qualcomm modems, delivering tailored features on time to reinforce Qualcomm's industry leadership.
- Co-designed and developed a feature that improved factory test and calibration power consumption for mobile phones by 18%.
- Resolved over 200 performance and stability issues identified in customer field testing, ensuring critical launch schedules were met.

Education

Bachelor of Technology (Electrical Engineering), Indian Institute of Technology, Indore (IIT) | India

Accomplishments and Awards

- Received the Orion Insta Award for outstanding contributions and efforts at Qualcomm.
- Secured 5th rank in District Talent Search Exam in Jaipur District.
- Received a commendation from Apple's executive management for outstanding software design and testing frameworks within the cross-functional 5G modem team.
- Granted company stocks and bonuses at Qualcomm as reward for cumulative performance(2020-2022).
- Promoted from Associate Engineer to Engineer at Qualcomm, 2021.

Co/Extra-curricular

- PGPM Placement Committee Vertical Head for Technology. Leading placement strategy and industry outreach for technology sector roles.
- Conducted teaching activities at various govt schools in Simrol village as well as events such as plantation drive old age home visit at IIT Indore(2015 – 2018).
- Member of Cultural committee, Entrepreneurship cell, Techno-cultural Fest Organising committee at IIT Indore(2015 – 2018).
- Directed and acted at my school, Kapil Gyanpeeth for Academic Year 2010 – 2012; led a team of 10 students to win inter-school street play competition.

